

Product / Package Information

Package	LFCSP - Sawn
Body Size (mm)	6 X 6 X 0.75 (4.7 EP)
Lead Count	36
Terminal Finish	100 Sn
MS Number	MS012370C

Environmental Information

RoHS Compliant	Yes
High Temperature Compliant	Yes
Halogen Free Compliant	Yes
REACH SVHC Compliant	Yes

Materials Declaration

Molding Compound

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level		
				Percentage (%)	PPM	Percentage (%)	PPM	
Other inorganic materials	Silica	60678-86-0	3.18E-02	84.50	845000	31.82		318164
Thermosets	Epoxy & Phenol Resin	Proprietary	5.64E-03	15.00	150000	5.65		56479
Other inorganic materials	Carbon black	1333-86-4	1.88E-04	0.50	5000	0.19		1883
Subtotal			3.76 E-02	100.00	1000000	37.65		376526

Leadframe

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level		
				Percentage (%)	PPM	Percentage (%)	PPM	
Copper & its alloys	Copper	7440-50-8	5.03 E-02	97.50	975000	50.34		503402
Copper & its alloys	Iron	7439-89-6	1.21 E-03	2.35	23500	1.21		12133
Copper & its alloys	Zinc	7440-66-6	6.19 E-05	0.12	1200	0.06		620
Copper & its alloys	Phosphorus	7723-14-0	1.55 E-05	0.03	300	0.02		155
Subtotal			5.16 E-02	100.00	1000000	51.63		516310

Internal Leadframe Plating

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level		
				Percentage (%)	PPM	Percentage (%)	PPM	
Precious metals	Silver	7440-22-4	6.20 E-04	100.0	1000000	0.62		6204

External Leadframe Plating

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level		
				Percentage (%)	PPM	Percentage (%)	PPM	
Tin & its alloys	Tin	7440-31-5	1.68 E-03	100.0	1000000	1.68		16810

Bond Wires

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level		
				Percentage (%)	PPM	Percentage (%)	PPM	
Copper & its alloys	Copper	7440-50-8	1.79 E-03	96.00	960000	1.79		17867
Precious metals	Palladium	7440-05-3	5.58 E-05	3.00	30000	0.06		558
Precious Metals	Gold	7440-57-5	1.86 E-05	1.00	10000	0.02		186
Subtotal			1.86 E-03	100.0	1000000	1.86		18611

Chip

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level		
				Percentage (%)	PPM	Percentage (%)	PPM	
Other inorganic materials	Doped Silicon	7440-21-3	5.40 E-03	100.0	1000000	5.40		54032

Die Attach

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level		
				Percentage (%)	PPM	Percentage (%)	PPM	
Precious metals	Silver	7440-22-4	8.86 E-04	77.00	770000	0.89		8860
Other organic materials	Acrylic resin	Proprietary	8.05 E-05	7.00	70000	0.08		805
Other organic materials	Acrylate	Proprietary	6.33 E-05	5.50	55000	0.06		633
Other organic materials	Polybutadiene derivative	Proprietary	5.18 E-05	4.50	45000	0.05		518
Other organic materials	Epoxy resin	Proprietary	2.88 E-05	2.50	25000	0.03		288
Other organic materials	Butadiene Copolymer	Proprietary	1.73 E-05	1.50	15000	0.02		173
Others	Additive	Proprietary	1.73 E-05	1.50	15000	0.02		173
Others	Peroxide	Proprietary	5.75 E-06	0.50	5000	0.01		58
Subtotal			1.15 E-03	100.0	1000000	1.15		11507

Package Totals	Weight (g)	Percentage (%)	PPM
	9.99 E-02	100	1000000

Note: The information provided in this declaration are true to the best of ADI's knowledge. ADI derived most of the information listed in this declaration from documents provided by third parties, and assumes no liability to any inaccuracy of such information.



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